Flip Chip International Appoints Terrence M. Lubsen as VP-Quality & Continuous Improvement

PHOENIX, Arizona, March 23, 2004---FlipChip International LLC announced today that it has appointed Terrence M. Lubsen as its Vice President of Quality and Continuous Improvement for its semiconductor wafer scale packaging and bumping business in Phoenix, Arizona.   Mr. Terrence Lubsen will report to Bob Forcier, President and CEO of FlipChip International. Mr. Lubsen's background includes over 30 yrs. of management experience in microelectronics packaging at Signetics/Philips Semiconductor, INDY Electronics, and Amkor Technology.

Bob Forcier, President and CEO of FlipChip International stated, "We are very pleased to have Terry Lubsen join FlipChip International as our Vice-President Quality. Terry's experience in Quality Systems and Continuous Improvement will bring a fresh insight and stability to FCI's Quality Programs which include our newly acquired Die Sales Division for dicing, tape/reel and inspection services." Mr. Lubsen said, "I am excited about joining the FlipChip International team. I look forward to the challenges as FCI continues to grow in this fast paced market".

FlipChip International, LLC is privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market.   Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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